



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

0755-83047638

ysbdt@szyoushang.cn

www.szyoushang.cn



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Features

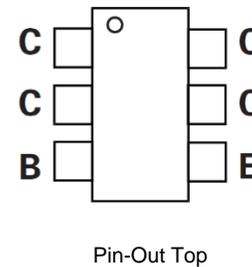
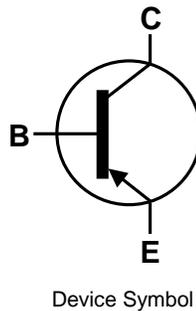
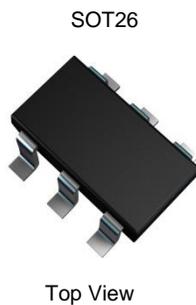
- $BV_{CEO} > -20V$
- $I_C = -2.5A$ Continuous Collector Current
- $I_{CM} = -6A$ Peak Pulse Current
- $R_{CE(sat)} = 96m\Omega$ for a Low Equivalent On-Resistance
- Low Saturation Voltage ($-220mV$ max @ 1A)
- h_{FE} Characterized up to -6A for High Current Gain Hold-Up

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.015 grams (Approximate)

Applications

- DC-DC Converters
- Power Management Functions
- Power Switches
- Motor Control



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-20	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Base Voltage	V _{EBO}	-7	V
Base Current	I _B	-500	mA
Continuous Collector Current	I _C	-2.5	A
Peak Pulse Collector Current	I _{CM}	-6	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

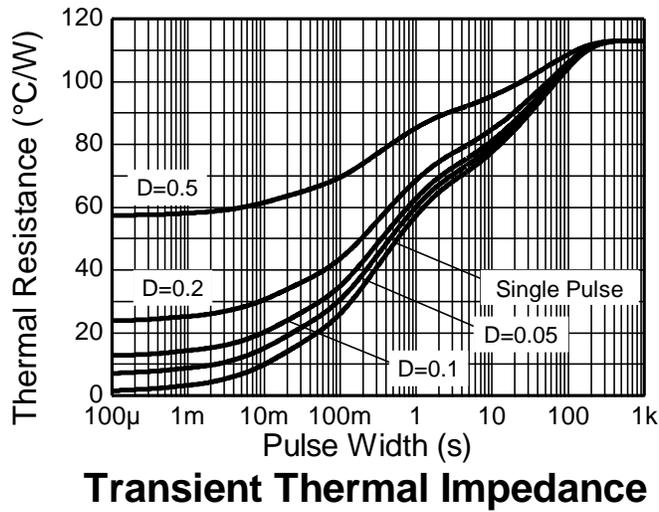
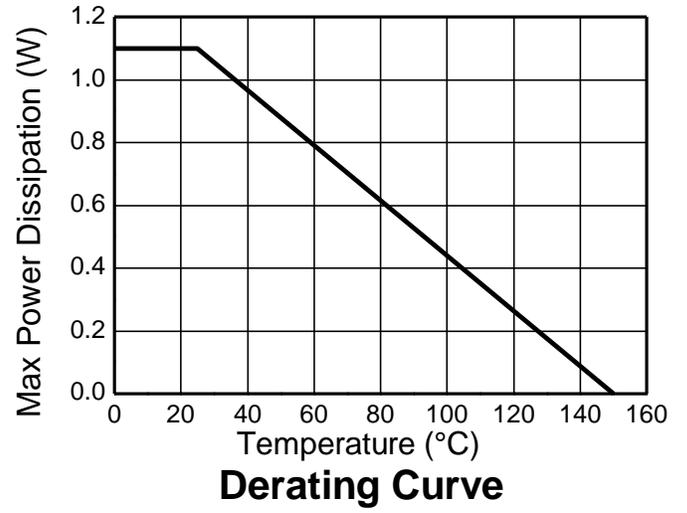
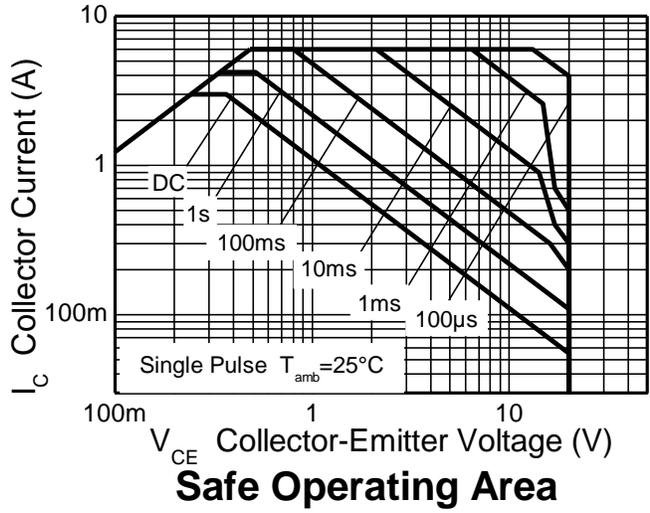
Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	P _D	1.1	W
		8.8	
Thermal Resistance, Junction to Ambient	R _{θJA}	1.7	mW/°C
		13.6	
Thermal Resistance, Junction to Ambient	R _{θJA}	113	°C/W
		73	
Thermal Resistance, Junction to Leads	R _{θJL}	30.01	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted with collector leads on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 - Same as Note 5, except the device is measured at t ≤ 5secs.
 - Thermal resistance from junction to solder-point (at the end of the collector leads).
 - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

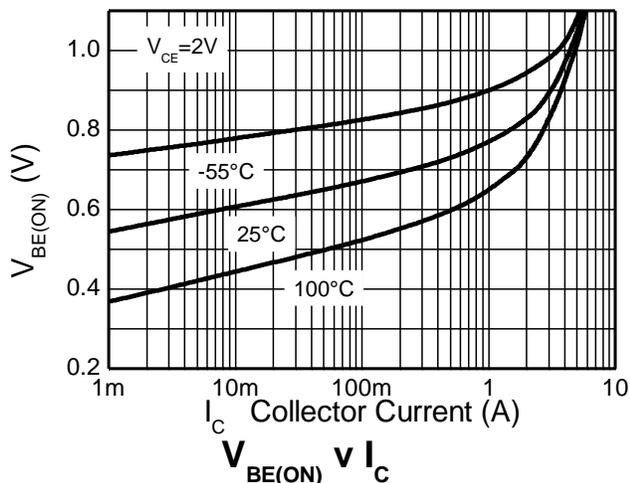
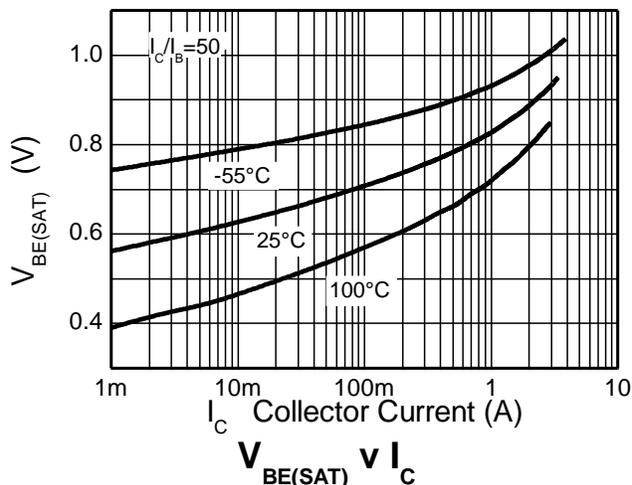
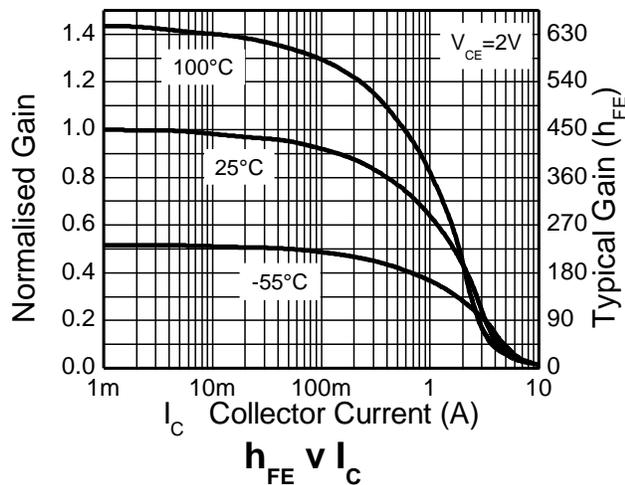
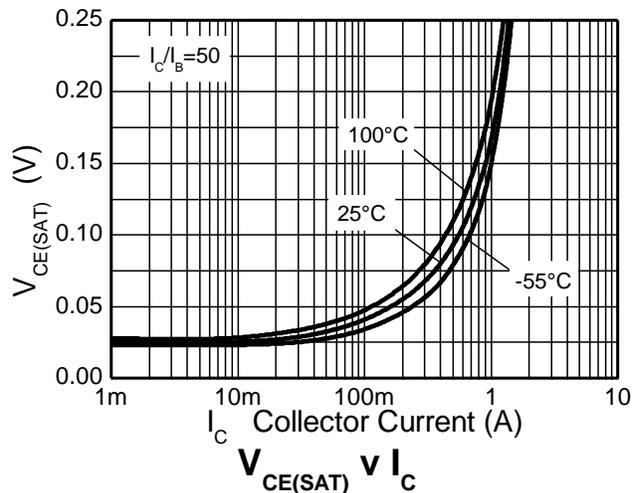
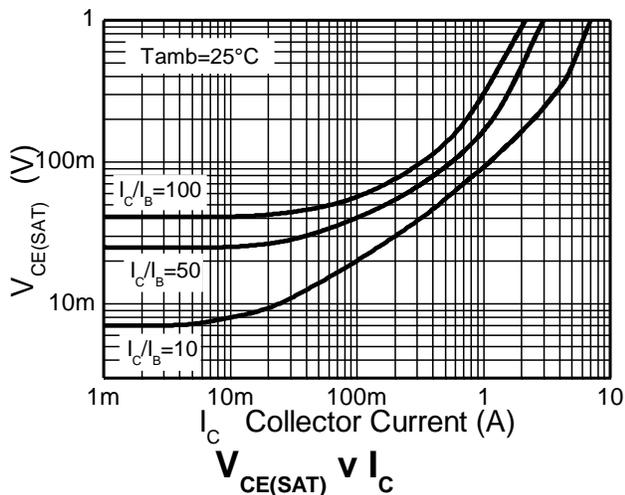


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

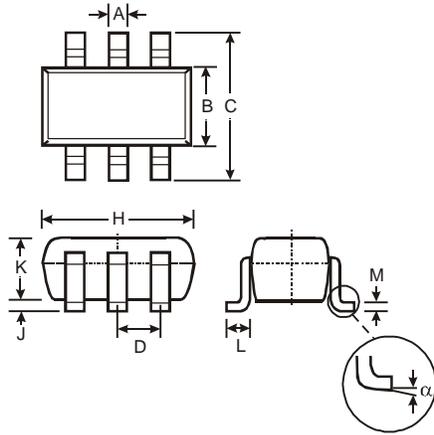
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	-20	-65	—	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	-20	-53	—	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.8	—	V	I _E = -100μA
Collector-Base Cutoff Current	I _{CBO}	—	<1	-100	nA	V _{CB} = -15V
Emitter Cutoff Current	I _{EBO}	—	<1	-100	nA	V _{EB} = -5V
Collector-Emitter Cutoff Current	I _{CES}	—	<1	-100	nA	V _{CEs} = -15V
ON CHARACTERISTICS (Note 9)						
DC Current Gain	h _{FE}	300	475	—	—	I _C = -10mA, V _{CE} = -2V
		300	450	—	—	I _C = -0.1A, V _{CE} = -2V
		150	230	—	—	I _C = -2A, V _{CE} = -2V
		15	30	—	—	I _C = -6A, V _{CE} = -2V
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	-19	-30	mV	I _C = -0.1A, I _B = -10mA
		—	-170	-220		I _C = -1A, I _B = -20mA
		—	-190	-250		I _C = -1.5A, I _B = -50mA
		—	-240	-350		I _C = -2.5A, I _B = -150mA
Base-Emitter Saturation Voltage	V _{BE(sat)}	—	-0.97	-1.05	V	I _C = -2.5A, I _B = -150mA
Base-Emitter Turn-On Voltage	V _{BE(on)}	—	-0.85	-0.95	V	I _C = -2.5A, V _{CE} = -2V
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f _T	150	180	—	MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz
Output Capacitance	C _{obo}	—	21	30	pF	V _{CB} = -10V, f = 1MHz
Turn-On Time	t _(on)	—	40	—	ns	V _{CC} = -10V, I _C = -1A
Turn-Off Time	t _(off)	—	670	—	ns	I _{B1} = -I _{B2} = -20mA

Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

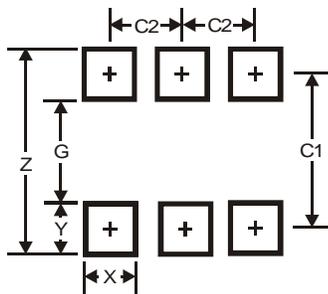


Package Outline Dimensions



SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95